

STGW20NB60H

N-CHANNEL 20A - 600V TO-247 PowerMESHTM IGBT

TYPE	V _{CES}	V _{CE(sat)}	Ic	
STGW20NB60H	600 V	< 2.8 V	20 A	

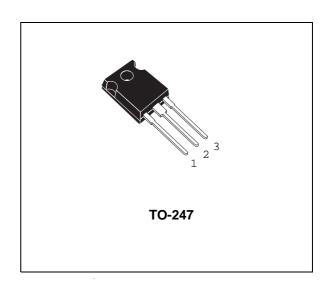
- HIGH INPUT IMPEDANCE (VOLTAGE DRIVEN)
- LOW ON-VOLTAGE DROP (V_{CESAT})
- LOW GATE CHARGE
- HIGH CURRENT CAPABILITY
- VERY HIGH FREQUENCY OPERATION
- OFF LOSSES INCLUDE TAIL CURRENT

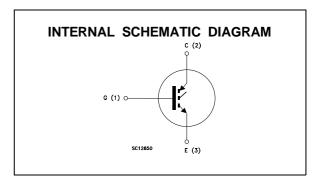
DESCRIPTION

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESHTM IGBTs, with outstanding perfomances. The suffix "H" identifies a family optimized to achieve very low switching times for high frequency applications (<120kHz).

APPLICATIONS

- HIGH FREQUENCY MOTOR CONTROLS
- WELDING EQUIPMENTS
- SMPS AND PFC IN BOTH HARD SWITCH AND RESONANT TOPOLOGIES





ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CES}	Collector-Emitter Voltage (V _{GS} = 0)	600	V
V _{ECR}	Emitter-Collector Voltage	20	V
V_{GE}	Gate-Emitter Voltage	± 20	V
Ic	Collector Current (continuous) at T _c = 25 °C	40	Α
Ic	Collector Current (continuous) at T _c = 100 °C	20	Α
I _{CM} (●)	Collector Current (pulsed)	160	Α
P _{tot}	Total Dissipation at T _c = 25 °C	150	W
	Derating Factor	1.2	W/°C
T _{stg}	Storage Temperature	-65 to 150	°C
Tj	Max. Operating Junction Temperature	150	°C

^(•) Pulse width limited by safe operating area

June 1999 1/8

THERMAL DATA

R _{thj-cas}	Thermal Resistance Junction-case	Max	0.83	°C/W
R _{thj-aml}	Thermal Resistance Junction-ambient	Max	30	oC/W
R _{thc-h}	Thermal Resistance Case-heatsink	Тур	0.1	°C/W

ELECTRICAL CHARACTERISTICS ($T_j = 25$ °C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{BR(CES)}	Collector-Emitter Breakdown Voltage	$I_C = 250 \mu\text{A}$ $V_{GE} = 0$	600			V
I _{CES}	Collector cut-off (V _{GE} = 0)	$V_{CE} = Max Rating$ $T_j = 25 ^{\circ}C$ $V_{CE} = Max Rating$ $T_j = 125 ^{\circ}C$			10 100	μΑ μΑ
I _{GES}	Gate-Emitter Leakage Current (V _{CE} = 0)	$V_{GE} = \pm 20 \text{ V}$ $V_{CE} = 0$			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
$V_{GE(th)}$	Gate Threshold Voltage	$V_{CE} = V_{GE}$ $I_C = 250 \mu A$	3		5	>
V _{CE(SAT)}	Collector-Emitter Saturation Voltage	$V_{GE} = 15 \text{ V}$ $I_{C} = 20 \text{ A}$ $V_{GE} = 15 \text{ V}$ $I_{C} = 20 \text{ A}$ $T_{j} = 125 ^{\circ}\text{C}$		2.3 1.9	2.8	V V

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g fs	Forward Transconductance	V _{CE} =25 V I _C = 20 A	7.0	10		S
Cies Coes Cres	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V _{CE} = 25 V f = 1 MHz V _{GE} = 0	1200 140 28	1700 200 40	2200 260 52	pF pF pF
Q _G Q _{GE} Q _{GC}	Total Gate Charge Gate-Emitter Charge Gate-Collector Charge	V _{CE} = 480 V I _C = 20 A V _{GE} = 15 V		110 13 51	145	nC nC nC
I _{CL}	Latching Current	$V_{clamp} = 480 \text{ V}$	80			А

SWITCHING ON

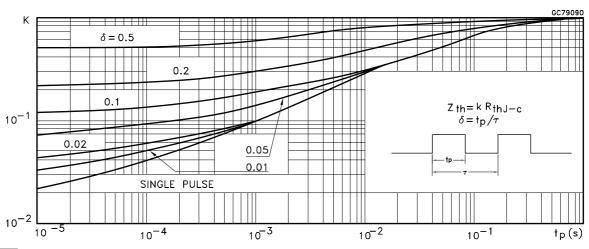
Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Delay Time Rise Time	V _{CC} = 480 V V _{GE} = 15 V	$I_C = 20 A$ $R_G = 10\Omega$		20 70		ns ns
(di/dt) _{on}	Turn-on Current Slope	$V_{CC} = 480 \text{ V}$ $R_G = 10 \Omega$	$I_C = 20 A$ $V_{GE} = 15 V$		350		A/μs
E _{on}	Turn-on Switching Losses	T _j = 125 °C	- '		300		μJ

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING OFF

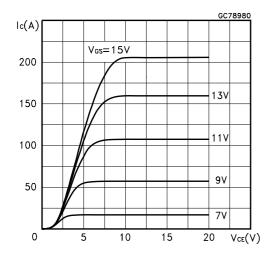
Symbol	Parameter	Test Co	nditions	Min.	Тур.	Max.	Unit
tc	Cross-Over Time	V _{CC} = 480 V	I _C = 20 A		115		ns
$t_r(v_{off})$	Off Voltage Rise Time	$R_{GE} = 10 \Omega$	$V_{GE} = 15 V$		32		ns
$t_d(off)$	Delay Time				170		ns
t _f	Fall Time				75		ns
E _{off} (**)	Turn-off Switching Loss				0.4		mJ
E _{ts}	Total Switching Loss				0.65		mJ
t _c	Cross-Over Time	VCC = 480 V	$I_{C} = 20 \text{ A}$		190		ns
$t_r(v_{off})$	Off Voltage Rise Time	$R_{GE} = 10 \Omega$	$V_{GE} = 15 \text{ V}$		55		ns
$t_d(off)$	Delay Time	T _j = 125 °C			210		ns
t _f	Fall Time				140		ns
E _{off} (**)	Turn-off Switching Loss				0.7		mJ
E _{ts}	Total Switching Loss				1.0		mJ

Thermal Impedance

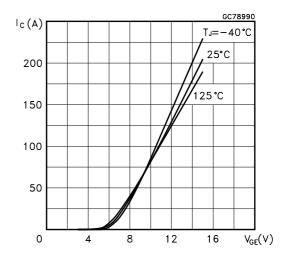


^(*) Pulse width limited by max. junction temperature
(*) Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %
(**)Losses Include Also The Tail (Jedec Standardization)

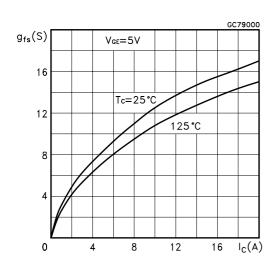
Output Characteristics



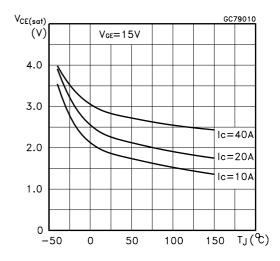
Transfer Characteristics



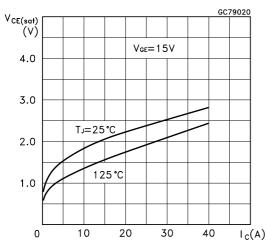
Transconductance



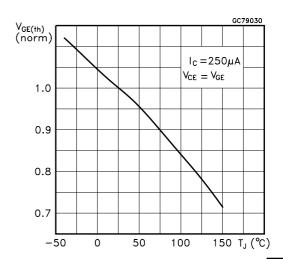
Collector-Emitter On Voltage vs Temperature



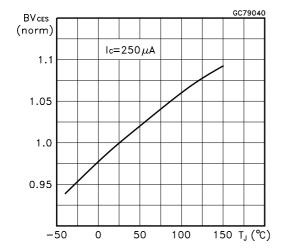
Collector-Emitter On Voltage vs Collector Current



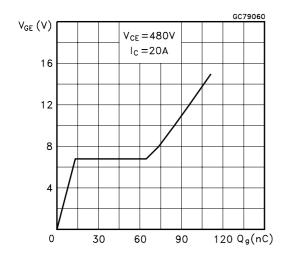
Gate Threshold vs Temperature



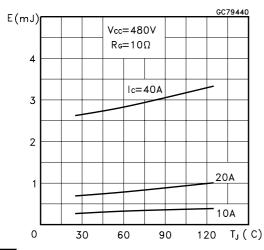
Normalized Breakdown Voltage vs Temperature



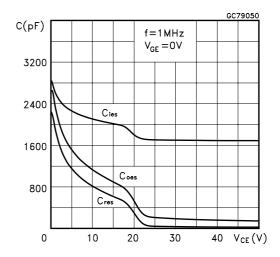
Gate Charge vs Gate-Emitter Voltage



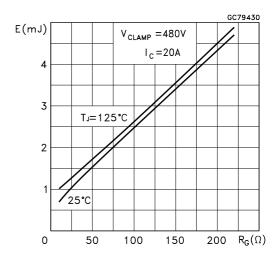
Total Switching Losses vs Temperature



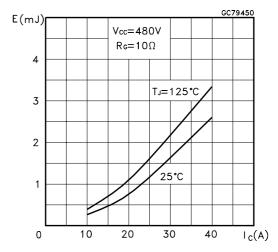
Capacitance Variations



Total Switching Losses vs Gate Resistance



Total Switching Losses vs Collector Current



477

Switching Off Safe Operating Area

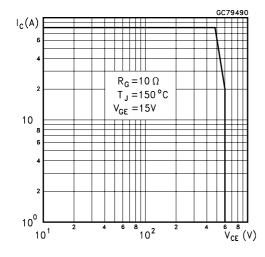


Fig. 1: Gate Charge test Circuit

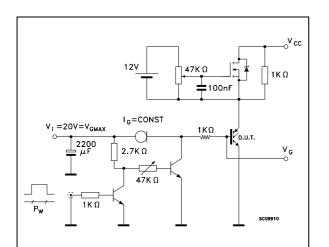


Fig. 2: Test Circuit For Inductive Load Switching

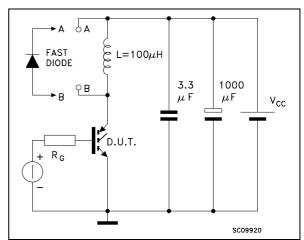
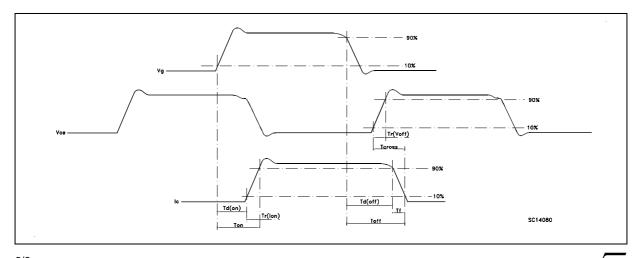
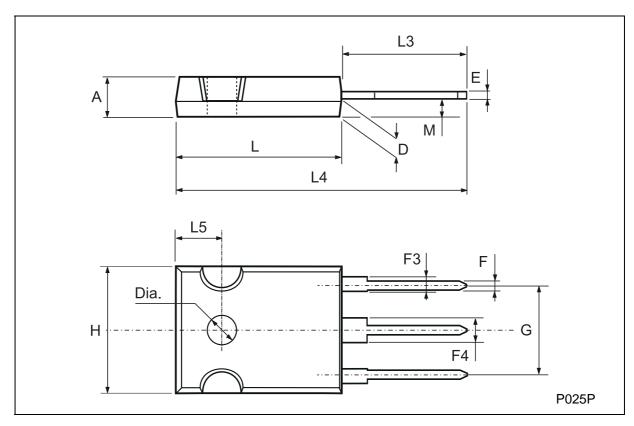


Fig. 3: Switching Waveforms



TO-247 MECHANICAL DATA

DIM.		mm			inch	
Diwi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	4.7		5.3	0.185		0.209
D	2.2		2.6	0.087		0.102
Е	0.4		0.8	0.016		0.031
F	1		1.4	0.039		0.055
F3	2		2.4	0.079		0.094
F4	3		3.4	0.118		0.134
G		10.9			0.429	
Н	15.3		15.9	0.602		0.626
L	19.7		20.3	0.776		0.779
L3	14.2		14.8	0.559		0.582
L4		34.6			1.362	
L5		5.5			0.217	
М	2		3	0.079		0.118



Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specification mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a trademark of STMicroelectronics

© 1999 STMicroelectronics – Printed in Italy – All Rights Reserved STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - China - Finland - France - Germany - Hong Kong - India - Italy - Japan - Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - U.S.A.

http://www.st.com

4